

## ABSTRACT

Disclosed herein are a mixed resin compound, a resin  
5 pipe, a process for producing said resin pipe, and a  
photosensitive drum. The resin compound meets at least one  
of the following requirements. It is a mixture of two or  
more kinds of resins blended in a specific manner, it  
undergoes annealing under specific conditions, and it has  
10 specific values of surface roughness, Vickers hardness,  
coefficient of linear expansion, flexural modulus, and  
thermal conductivity. The resin pipe is suitable for use as  
the cylindrical base of the photosensitive drum for  
electrophotographic machines, such as copying machines,  
15 facsimiles, and printers. It is superior in surface  
smoothness, dimensional stability, coatability, and  
handlability, and hence it is very little vulnerable to  
damage during handling and dimensional change due to resin  
shrinkage and is superior in heat resistance (desirable for  
20 solvent removal) and mechanical strength (desirable for  
flange fitting).